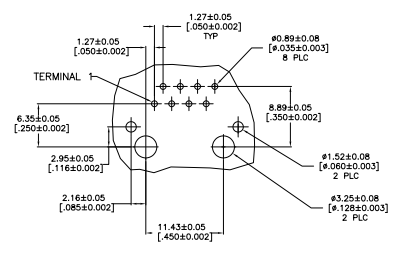
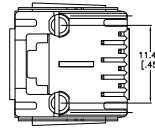
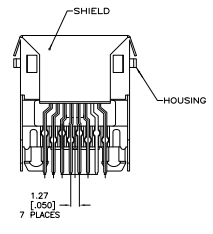
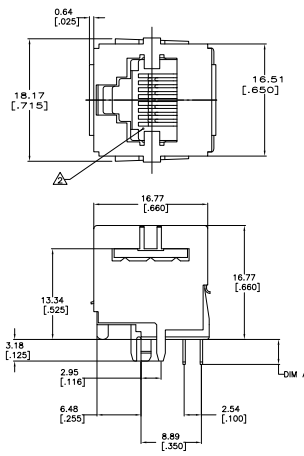
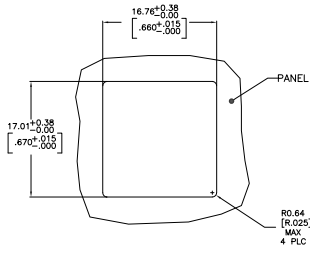


THIS DRAWING IS UNPUBLISHED
 ALL RIGHTS RESERVED

REV	DATE	DESCRIPTION	BY	CHK	APP
AA	00				
D1		REVISED PER ECD-11-004835			



RECOMMENDED PRINTED
 CIRCUIT BOARD LAYOUT
 COMPONENT SIDE SHOWN



RECOMMENDED PANEL
 CUTOUT

- MATERIAL:
 HOUSING - POLYESTER MOLDING COMPOUND, COLOR: BLACK
 TERMINALS - 0.35[0.138] THICK PHOS BRONZE PLATED WITH 1.27μm[0.00050] MIN THICK GOLD IN LOCALIZED AREA AND 3.81μm[0.00150] MIN THICK MATTE TIN IN SOLDER AREA OVER 1.27μm[0.00050] MIN THICK NICKEL UNDERPLATE
 SHIELD - COPPER ZINC ALLOY PLATED WITH 3.0μm [0.00120] MIN THICK REFLOWED TIN.

CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68 AND REA BULLETIN 345-81, PE-76 SPECIFICATION FOR MODULAR TELEPHONE HARDWARE.

2.79-3.30 [0.120±0.010]	5557969-2
2.79-3.56 [0.125±0.015]	5557969-1
DIM A	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		CONTROLLED BY: TE Connectivity CONTROLLED BY: TE Connectivity CONTROLLED BY: TE Connectivity CONTROLLED BY: TE Connectivity	
DIMENSIONS: (mm INCHES) UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS DECIMAL DIMENSIONS ARE IN MILLIMETERS FRACTIONAL DIMENSIONS ARE IN INCHES	DRAWN BY: TE Connectivity CHECKED BY: TE Connectivity DATE: 108-1163 REV: 114-2048	PART NUMBER: 5557969 REV: 1 DATE: 11/11/11	CUSTOMER DRAWING: 5557969 REV: 1 DATE: 11/11/11